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Product Change Notification - JAON-22WYMK349

Date: 29 Sep 2016
Product Category: Analog (Thermal, Power Management & Safety)
Notification subject: CCB 2748 Final Notice: Qualification of 84-1LMISR8 die attach material for selected Micrel products available in 8L SOIC package at UNIS assembly site.
Notification text: **PCN Status:**
 Final notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 84-1LMISR8 die attach material for selected Micrel products available in 8L SOIC package at UNIS assembly site.

Pre Change:

Using 2600AT die attach material

Post Change:

Using 84-1LMISR8 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UNIS assembly site	UNIS assembly site
Wire material	Au wire	Au wire
Die attach material	2600AT	84-1LMISR8
Molding compound material	G600	G600
Lead frame material	A194	A194
Lead Finish	Sn	Sn

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying 84-1LMISR8 die attach material. The 2600AT die attach material will no longer be available for use to assemble selected Micrel products in 8L SOIC package at UNIS assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
November 15, 2016 (date code: 1646)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2016					October 2016				November 2016			
Workweek	35	36	37	38	39	40	41	42	43	44	45	46	47
Qual Report Availability					X								
Final PCN Issue Date					X								
Estimated Implementation Date												X	

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
September 29, 2016: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-22WYMK349_Qual Report.pdf](#)
[PCN_JAON-22WYMK349_Affected CPN.pdf](#)
[PCN_JAON-22WYMK349_Affected CPN.xls](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22WYMK349
CATALOG_PART_NBR
MIC37101-1.5YM
MIC37101-1.5YM-TR
MIC37101-1.65YM
MIC37101-1.65YM-TR
MIC37101-1.8YM
MIC37101-1.8YM-TR
MIC37101-2.1YM
MIC37101-2.1YM-TR
MIC37101-2.5YM
MIC37101-2.5YM-TR
MIC37101-3.3YM
MIC37101-3.3YM-TR
MIC37102YM
MIC37102YM-TR
MIC37152YM
MIC37152YM-TR
MIC39101-1.8YM
MIC39101-1.8YM-TR
MIC39101-2.5YM
MIC39101-2.5YM-TR
MIC39101-3.3YM
MIC39101-3.3YM-TR
MIC39101-5.0YM
MIC39101-5.0YM-TR
MIC39102YM
MIC39102YM-TR
MIC4680-3.3YM
MIC4680-3.3YM-TR
MIC4680-5.0YM
MIC4680-5.0YM-TR
MIC4680YM
MIC4680YM-TR
MIC4681YM
MIC4681YM-TR
MIC4682YM
MIC4682YM-TR
MIC4684YM
MIC4684YM-TR
MIC4690YM
MIC4690YM-TR
SPN030027Y
SPN030027Y-TR